

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	204009	(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)	USPAT	OR	ON	2005/12/16 13:54
L2	85614	L1 and(correct\$3 or error or inclinat\$3 or skew or slant or tilt\$3 or deviation)	USPAT	OR	ON	2005/12/16 13:41
L3	0	L2 and(turn\$3 or rotat\$3 or moving)with circumferential and(correct\$3 or error)with deviat\$3 and(CCD or camera or sensor\$1 or detector\$1)with serpentine and coordinat\$3	USPAT	OR	ON	2005/12/16 14:09
L4	18	L2 and(turn\$3 or rotat\$3 or moving)and(circumferential or circle)and(correct\$3 or error)with deviat\$3 and(CCD or camera or sensor\$1 or detector\$1)with(serpentine or sprial or circle)and coordinat\$3	USPAT	OR	ON	2005/12/16 13:44
L5	17	L4 and @ad<"20001121"	USPAT	OR	ON	2005/12/16 13:58
L6	683	correct\$3 and bump and block and (plurality or plural\$1)and (wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)and(inclinat\$3 or shift\$3 or slopes or skew)	USPAT	OR	ON	2005/12/16 13:56
L7	23	L6 and(CCD or camera or sensor\$1 or detector\$1)and scann\$3 near3(serpentine or sprial or circle)	USPAT	OR	ON	2005/12/16 13:58
L8	18	L7 and @ad<"20001121"	USPAT	OR	ON	2005/12/16 13:58
L9	16	L8 and (detect\$3 or determine)and mark\$3	USPAT	OR	ON	2005/12/16 14:04
L10	0	L9 and(turn\$3 or rotat\$3 or moving)with circumferential and(correct\$3 or error)with deviat\$3 and(CCD or camera or sensor\$1 or detector\$1)with(sprial or serpentine or zig adj zag) and coordinat\$3	USPAT	OR	ON	2005/12/16 14:10
L11	0	L9 and(turn\$3 or rotat\$3 or moving)and(circumferential or circle) and(correct\$3 or error)with deviat\$3 and(CCD or camera or sensor\$1 or detector\$1)with(sprial or serpentine or zig adj zag) and coordinat\$3	USPAT	OR	ON	2005/12/16 14:11

L12	0	L9 and(turn\$3 or rotat\$3 or moving)and(circumferential or circle) and(correct\$3 or error)and deviat\$3 and(CCD or camera or sensor\$1 or détector\$1)and(sprial or serpentine or zig adj zag) and coordinat\$3	USPAT	OR	ON	2005/12/16 14:11
-----	---	---	-------	----	----	------------------

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	683	correct\$3 and bump and block and (plurality or plural\$1)and (wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)and(inclinat\$3 or shift\$3 or slopes or skew)	USPAT	OR	ON	2005/12/16 14:26
L2	21	L1 and(CCD or camera or sensor\$1 or detector\$1)and scann\$3 near3(serpentine or sprial or circle)and(detect\$3 or determine)and mark\$3	USPAT	OR	ON	2005/12/16 14:20
L3	89327	382/145,151,181,286, "287", "289, 312".ccls.	USPAT	OR	ON	2005/12/16 14:27
L4	73	L3 and L1	USPAT	OR	ON	2005/12/16 14:27
L5	8	L4 and L2	USPAT	OR	ON	2005/12/16 14:28
L6	73	L1 and L3	USPAT	OR	ON	2005/12/16 14:28
L7	8	L2 and L6	USPAT	OR	ON	2005/12/16 14:39
L9	3701	438/14,460,612,613,614.ccls.	USPAT	OR	ON	2005/12/16 14:40
L10	5	L1 and L9	USPAT	OR	ON	2005/12/16 14:40
L11	0	L10 and L2	USPAT	OR	ON	2005/12/16 14:41
L12	967	257/e23.179.ccls.	USPAT	OR	ON	2005/12/16 14:41
L13	3	L1 and L12	USPAT	OR	ON	2005/12/16 14:41
L14	0	L13 and L2	USPAT	OR	ON	2005/12/16 14:42

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	(correct\$3 and bump and block and (plurality or plural\$1)and (wafer\$I or semiconductor\$I or chip\$I or substrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)and(inclinat\$3 or shift\$3 or slopes or skew)and(CCD or camera or sensor\$1 or detector\$1)and scann\$3 near3(serpentine or sprial or circle)and(detect\$3 or determine)and mark\$3).clm.	US-PGPUB	OR	ON	2005/12/16 14:46

Dial g DataStar



options

logout

feedback

help

databases

easy
search

Advanced Search: INSPEC - 1969 to date (INZZ)

limit

Search history:

No.	Database	Search term	Info added since	Results	
1	INZZ	wafer OR semiconductor OR chip OR substrat OR IC OR intergrated ADJ circuit OR PCB OR printed ADJ circuit ADJ board OR PWB OR printed ADJ wiring ADJ board	unrestricted	691240	show titles
2	INZZ	L1 AND correct* AND bump AND block AND (plurality OR plural*) AND (CCD OR camera OR sensor* OR detector*) AND scann* ADJ (serpentine OR sprial OR circle)	unrestricted	0	-
3	INZZ	L1 AND correct* AND bump AND block AND (plurality OR plural*) AND (inclinat* OR shift* OR slopes OR skew OR deviation)	unrestricted	0	-
4	INZZ	L1 AND correct* AND bump AND (inclinat* OR shift* OR slopes OR skew OR deviation)	unrestricted	0	-
5	INZZ	L1 AND (CCD OR camera OR sensor OR detector) AND scann* AND (serpentine OR sprial OR circle)	unrestricted	0	-
6	INZZ	L1 AND (CCD OR camera OR sensor OR detector) AND scann*	unrestricted	0	-
7	INZZ	L1 AND (CCD OR camera OR sensor OR detector) AND scanning	unrestricted	1	show titles
8	INZZ	L1 AND L7	unrestricted	2	show titles
9	INZZ	L8 AND (serpentine OR sprial OR circle)	unrestricted	1	show titles

[hide](#) | [delete all search steps...](#) | [delete individual search steps...](#)
Enter your search term(s): [Search tips](#) ☐ Thesaurus mapping
 whole document

 Information added since: or: none
 (YYYYMMDD)

search

Day : Friday
Date: 12/16/2005


PALM INTRANET

Time: 17:09:29

Inventor Name Search Result

Your Search was:

Last Name = NARITA

First Name = SHORIKI

Application#	Patent#	Status	Date Filed	Title	Inventor Name
08435616	5648729	150	05/05/1995	BOARD POSITIONING METHOD AND APPARATUS OF THE METHODS	NARITA, SHORIKI
08504654	5769236	150	07/20/1995	COMPONENT COLLECTIVE AND COMPONENT COLLECTIVE FEEDING APPARATUS	NARITA, SHORIKI
08825499	5955876	150	03/31/1997	BOARD POSITIONING APPARATUS	NARITA, SHORIKI
09335779	6302317	150	06/18/1999	BUMP BONDING APPARATUS AND METHOD	NARITA, SHORIKI
09423375	6098868	150	11/04/1999	BUMP FORMING METHOD AND BUMP BONDER	NARITA, SHORIKI
09690746	6329640	150	10/18/2000	Heating apparatus for bump bonding, bump bonding method and bump forming apparatus, and semiconductor wafer	NARITA, SHORIKI
09719768	6787391	150	12/18/2000	METHOD OF FORMING BUMPS ON A WAFER UTILIZING A POST-HEATING	NARITA, SHORIKI
09911801	6494358	150	07/25/2001	BUMP BONDING APPARATUS AND METHOD	NARITA, SHORIKI
09911802	6568580	150	07/25/2001	BUMP BONDING APPARATUS AND METHOD	NARITA, SHORIKI
09955110	6392202	150	09/19/2001	HEATING APPARATUS FOR BUMP BONDING, BUMP BONDING METHOD AND BUMP FORMING APPARATUS, AND SEMICONDUCTOR WAFER	NARITA, SHORIKI
09988704	Not Issued	71	11/20/2001	Method and apparatus for correcting inclination of IC on semiconductor wafer	NARITA, SHORIKI

<u>10019700</u>	<u>6818975</u>	150	01/02/2002	ELECTRIC CHARGE GENERATING SEMICONDUCTOR SUBSTRATE BUMP FORMING DEVICE, METHOD OF REMOVING ELECTRIC CHARGE FROM ELECTRIC CHARGE GENERATING SEMICONDUCTOR SUBSTRATE DEVICE FOR REMOVING ELECTRIC CHARGE FROM ELECTRIC CHARGE GENERATING SEMICONDUCTOR SUBSTRATE, AND ELECT	NARITA, SHORIKI
<u>10332026</u>	<u>6910613</u>	150	01/02/2003	DEVICE AND METHOD FOR FORMING BUMP	NARITA, SHORIKI
<u>10415587</u>	Not Issued	93	04/30/2003	BUMP FORMATION METHOD AND BUMP FORMING APPARATUS TO SEMICONDUCTOR WAFER	NARITA, SHORIKI
<u>10536361</u>	Not Issued	20	05/26/2005	Component-supplying head device, component-supplying device, component-mounting device, and method for moving mounting head portion	NARITA, SHORIKI
<u>10537406</u>	Not Issued	20	06/02/2005	Parts feeder	NARITA, SHORIKI
<u>10651103</u>	Not Issued	94	08/29/2003	BUMP FORMING APPARATUS FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVAL METHOD FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVING UNIT FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, AND CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE	NARITA, SHORIKI
<u>10651199</u>	Not Issued	95	08/29/2003	BUMP FORMING APPARATUS FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVAL METHOD FOR	NARITA, SHORIKI

				CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVING UNIT FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, AND CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE	
<u>10761412</u>	Not Issued	30	01/22/2004	Method of forming bumps on a wafer utilizing a post-heating operation, and an apparatus therefore	NARITA, SHORIKI
<u>11114084</u>	Not Issued	41	04/26/2005	Apparatus and method for forming bump	NARITA, SHORIKI

Inventor Search Completed: No Records to Display.

Search Another: Inventor	Last Name	First Name	
	<input type="text" value="NARITA"/>	<input type="text" value="SHORIKI"/>	

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | [Home page](#)

Day : Friday
Date: 12/16/2005


PALM INTRANET

Time: 17:09:41

Inventor Name Search Result

Your Search was:

Last Name = IKEYA

First Name = MASAHIKO

Application#	Patent#	Status	Date Filed	Title	Inventor Name
09423375	6098868	150	11/04/1999	BUMP FORMING METHOD AND BUMP BONDER	IKEYA, MASAHIKO
09719768	6787391	150	12/18/2000	METHOD OF FORMING BUMPS ON A WAFER UTILIZING A POST-HEATING	IKEYA, MASAHIKO
09988704	Not Issued	71	11/20/2001	Method and apparatus for correcting inclination of IC on semiconductor wafer	IKEYA, MASAHIKO
10019700	6818975	150	01/02/2002	ELECTRIC CHARGE GENERATING SEMICONDUCTOR SUBSTRATE BUMP FORMING DEVICE, METHOD OF REMOVING ELECTRIC CHARGE FROM ELECTRIC CHARGE GENERATING SEMICONDUCTOR SUBSTRATE DEVICE FOR REMOVING ELECTRIC CHARGE FROM ELECTRIC CHARGE GENERATING SEMICONDUCTOR SUBSTRATE, AND ELECT	IKEYA, MASAHIKO
10234118	Not Issued	93	09/05/2002	COMPONENT MOUNTING APPARATUS AND COMPONENT MOUNTING METHOD	IKEYA, MASAHIKO
10332026	6910613	150	01/02/2003	DEVICE AND METHOD FOR FORMING BUMP	IKEYA, MASAHIKO
10415587	Not Issued	93	04/30/2003	BUMP FORMATION METHOD AND BUMP FORMING APPARATUS TO SEMICONDUCTOR WAFER	IKEYA, MASAHIKO

<u>10651103</u>	Not Issued	94	08/29/2003	BUMP FORMING APPARATUS FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVAL METHOD FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVING UNIT FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, AND CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE	IKEYA, MASAHIKO
<u>10651199</u>	Not Issued	95	08/29/2003	BUMP FORMING APPARATUS FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVAL METHOD FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVING UNIT FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, AND CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE	IKEYA, MASAHIKO
<u>10761412</u>	Not Issued	30	01/22/2004	Method of forming bumps on a wafer utilizing a post-heating operation, and an apparatus therefore	IKEYA, MASAHIKO
<u>11114084</u>	Not Issued	41	04/26/2005	Apparatus and method for forming bump	IKEYA, MASAHIKO

Inventor Search Completed: No Records to Display.

Search Another: Inventor

Last Name	First Name	
<input type="text" value="IKEYA"/>	<input type="text" value="MASAHIKO"/>	<input type="button" value="Search"/>

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | [Home page](#)

Day : Friday
Date: 12/16/2005


PALM INTRANET

Time: 17:09:54

Inventor Name Search Result

Your Search was:

Last Name = TSUBOI

First Name = YASUTAKA

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<u>08678658</u>	<u>5825914</u>	150	07/11/1996	COMPONENT DETECTION METHOD	TSUBOI, YASUTAKA
<u>09069203</u>	<u>5872863</u>	150	04/29/1998	COMPONENT DETECTION METHOD	TSUBOI, YASUTAKA
<u>09622825</u>	<u>6542238</u>	150	10/12/2000	ELECTRONIC COMPONENT MOUNTING APPARATUS	TSUBOI, YASUTAKA
<u>09988704</u>	Not Issued	71	11/20/2001	Method and apparatus for correcting inclination of IC on semiconductor wafer	TSUBOI, YASUTAKA
<u>10019700</u>	<u>6818975</u>	150	01/02/2002	ELECTRIC CHARGE GENERATING SEMICONDUCTOR SUBSTRATE BUMP FORMING DEVICE, METHOD OF REMOVING ELECTRIC CHARGE FROM ELECTRIC CHARGE GENERATING SEMICONDUCTOR SUBSTRATE DEVICE FOR REMOVING ELECTRIC CHARGE FROM ELECTRIC CHARGE GENERATING SEMICONDUCTOR SUBSTRATE, AND ELECT	TSUBOI, YASUTAKA
<u>10234118</u>	Not Issued	93	09/05/2002	COMPONENT MOUNTING APPARATUS AND COMPONENT MOUNTING METHOD	TSUBOI, YASUTAKA
<u>10415587</u>	Not Issued	93	04/30/2003	BUMP FORMATION METHOD AND BUMP FORMING APPARATUS TO SEMICONDUCTOR WAFER	TSUBOI, YASUTAKA
<u>10651103</u>	Not Issued	94	08/29/2003	BUMP FORMING APPARATUS FOR CHARGE	TSUBOI, YASUTAKA

				APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVAL METHOD FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVING UNIT FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, AND CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE	
<u>10651199</u>	Not Issued	95	08/29/2003	BUMP FORMING APPARATUS FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVAL METHOD FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVING UNIT FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, AND CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE	TSUBOI, YASUTAKA

Inventor Search Completed: No Records to Display.

Search Another: Inventor **Last Name** **First Name**

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | [Home page](#)

Day : Friday
Date: 12/16/2005


PALM INTRANET

Time: 17:10:14

Inventor Name Search Result

Your Search was:

Last Name = MAE

First Name = TAKAHARU

Application#	Patent#	Status	Date Filed	Title	Inventor Name
06891028	4763811	150	07/31/1986	PARTS FEEDER	MAE, TAKAHARU
09335779	6302317	150	06/18/1999	BUMP BONDING APPARATUS AND METHOD	MAE, TAKAHARU
09423375	6098868	150	11/04/1999	BUMP FORMING METHOD AND BUMP BONDER	MAE, TAKAHARU
09690746	6329640	150	10/18/2000	Heating apparatus for bump bonding, bump bonding method and bump forming apparatus, and semiconductor wafer	MAE, TAKAHARU
09719768	6787391	150	12/18/2000	METHOD OF FORMING BUMPS ON A WAFER UTILIZING A POST-HEATING	MAE, TAKAHARU
09830508	6619535	150	04/27/2001	WORKING METHOD FOR HOLDING A WORK OBJECT BY SUCTION	MAE, TAKAHARU
09911801	6494358	150	07/25/2001	BUMP BONDING APPARATUS AND METHOD	MAE, TAKAHARU
09911802	6568580	150	07/25/2001	BUMP BONDING APPARATUS AND METHOD	MAE, TAKAHARU
09955110	6392202	150	09/19/2001	HEATING APPARATUS FOR BUMP BONDING, BUMP BONDING METHOD AND BUMP FORMING APPARATUS, AND SEMICONDUCTOR WAFER	MAE, TAKAHARU
09988704	Not Issued	71	11/20/2001	Method and apparatus for correcting inclination of IC on semiconductor wafer	MAE, TAKAHARU
10019700	6818975	150	01/02/2002	ELECTRIC CHARGE GENERATING SEMICONDUCTOR	MAE, TAKAHARU

				SUBSTRATE BUMP FORMING DEVICE, METHOD OF REMOVING ELECTRIC CHARGE FROM ELECTRIC CHARGE GENERATING SEMICONDUCTOR SUBSTRATE DEVICE FOR REMOVING ELECTRIC CHARGE FROM ELECTRIC CHARGE GENERATING SEMICONDUCTOR SUBSTRATE, AND ELECT	
<u>10324001</u>	Not Issued	41	12/20/2002	Apparatus and method for mounting electronic components	MAE, TAKAHARU
<u>10332026</u>	<u>6910613</u>	150	01/02/2003	DEVICE AND METHOD FOR FORMING BUMP	MAE, TAKAHARU
<u>10415587</u>	Not Issued	93	04/30/2003	BUMP FORMATION METHOD AND BUMP FORMING APPARATUS TO SEMICONDUCTOR WAFER	MAE, TAKAHARU
<u>10508460</u>	Not Issued	20	10/18/2004	Electronic component mounting method and apparatus and ultrasonic bonding head	MAE, TAKAHARU
<u>10651103</u>	Not Issued	94	08/29/2003	BUMP FORMING APPARATUS FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVAL METHOD FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVING UNIT FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, AND CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE	MAE, TAKAHARU
<u>10651199</u>	Not Issued	95	08/29/2003	BUMP FORMING APPARATUS FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVAL METHOD FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE	MAE, TAKAHARU

				REMOVING UNIT FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, AND CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE	
<u>10761412</u>	Not Issued	30	01/22/2004	Method of forming bumps on a wafer utilizing a post-heating operation, and an apparatus therefore	MAE, TAKAHARU
<u>11114084</u>	Not Issued	41	04/26/2005	Apparatus and method for forming bump	MAE, TAKAHARU

Inventor Search Completed: No Records to Display.

Search Another: Inventor	Last Name	First Name	
	<input type="text" value="MAE"/>	<input type="text" value="TAKAHARU"/>	<input type="button" value="Search"/>

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | [Home page](#)

Day : Friday
Date: 12/16/2005


PALM INTRANET

Time: 17:10:25

Inventor Name Search Result

Your Search was:

Last Name = KANAYAMA

First Name = SHINJI

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<u>08098813</u>	<u>5462626</u>	150	07/29/1993	A METHOD OF BONDING AN LEAD AND A TOOL THERFOR	KANAYAMA, SHINJI
<u>08413441</u>	<u>5854745</u>	150	03/30/1995	METHOD AND APPARATUS FOR MOUNTING ELECTRONIC COMPONENT	KANAYAMA, SHINJI
<u>08496691</u>	<u>5582341</u>	150	06/29/1995	BONDING APPARATUS FOR TERMINAL COMPONENT	KANAYAMA, SHINJI
<u>08569937</u>	<u>5894657</u>	150	12/08/1995	MOUNTING APPARATUS FOR ELECTRONIC COMPONENT	KANAYAMA, SHINJI
<u>08589005</u>	<u>5783915</u>	150	01/19/1996	LINEAR ACTUATING APPARATUS	KANAYAMA, SHINJI
<u>09029391</u>	<u>6129203</u>	150	02/27/1998	IC DISCARDING APPARATUS FOR FLIP CHIP MOUNTING FACILITY	KANAYAMA, SHINJI
<u>09119974</u>	<u>6017812</u>	150	07/21/1998	BUMP BONDING METHOD AND BUMP BONDING APPARATUS	KANAYAMA, SHINJI
<u>09122901</u>	<u>6467158</u>	150	07/27/1998	COMPONENT FEEDER	KANAYAMA, SHINJI
<u>09155720</u>	<u>6055724</u>	150	10/02/1998	METHOD AND DEVICE FOR SEALING IC CHIP	KANAYAMA, SHINJI
<u>09254687</u>	<u>6332268</u>	150	03/16/1999	METHOD AND APPARATUS FOR PACKAGING IC CHIP, AND TAPE-SHAPED CARRIER TO BE USED THEREFOR	KANAYAMA, SHINJI
<u>09266928</u>	<u>6264704</u>	150	03/12/1999	METHOD AND APPARATUS FOR MOUNTING COMPONENT	KANAYAMA, SHINJI
<u>09335779</u>	<u>6302317</u>	150	06/18/1999	BUMP BONDING APPARATUS AND METHOD	KANAYAMA, SHINJI

<u>09354087</u>	<u>6321973</u>	150	07/15/1999	BUMP JOINING METHOD	KANAYAMA, SHINJI
<u>09373957</u>	<u>6193136</u>	150	08/13/1999	COMPONENT MOUNTING METHOD AND APPARATUS	KANAYAMA, SHINJI
<u>09388705</u>	Not Issued	161	09/02/1999	COMPONENT MOUNTING TOOL	KANAYAMA, SHINJI
<u>09446031</u>	<u>6647616</u>	150	12/15/1999	BUMP BONDING UNIT WITH TRAY STORAGE AND TRANSPORT APPARATUSES	KANAYAMA, SHINJI
<u>09690746</u>	<u>6329640</u>	150	10/18/2000	Heating apparatus for bump bonding, bump bonding method and bump forming apparatus, and semiconductor wafer	KANAYAMA, SHINJI
<u>09719768</u>	<u>6787391</u>	150	12/18/2000	METHOD OF FORMING BUMPS ON A WAFER UTILIZING A POST-HEATING	KANAYAMA, SHINJI
<u>09756307</u>	<u>6467670</u>	150	01/08/2001	METHOD AND APPARATUS FOR MOUNTING COMPONENT	KANAYAMA, SHINJI
<u>09763959</u>	<u>6439447</u>	150	02/28/2001	BUMP JOINING JUDGING DEVICE AND METHOD, AND SEMICONDUCTOR COMPONENT PRODUCTION DEVICE AND METHOD	KANAYAMA, SHINJI
<u>09830508</u>	<u>6619535</u>	150	04/27/2001	WORKING METHOD FOR HOLDING A WORK OBJECT BY SUCTION	KANAYAMA, SHINJI
<u>09873347</u>	<u>6506222</u>	150	06/05/2001	METHOD AND APPARATUS FOR MOUNTING COMPONENT	KANAYAMA, SHINJI
<u>09911801</u>	<u>6494358</u>	150	07/25/2001	BUMP BONDING APPARATUS AND METHOD	KANAYAMA, SHINJI
<u>09911802</u>	<u>6568580</u>	150	07/25/2001	BUMP BONDING APPARATUS AND METHOD	KANAYAMA, SHINJI
<u>09955110</u>	<u>6392202</u>	150	09/19/2001	HEATING APPARATUS FOR BUMP BONDING, BUMP BONDING METHOD AND BUMP FORMING APPARATUS, AND SEMICONDUCTOR WAFER	KANAYAMA, SHINJI
<u>09964404</u>	<u>6572005</u>	150	09/28/2001	BUMP JOINING METHOD	KANAYAMA, SHINJI
<u>09988704</u>	Not	71	11/20/2001	Method and apparatus for	KANAYAMA,

	Issued			correcting inclination of IC on semiconductor wafer	SHINJI
<u>10019700</u>	<u>6818975</u>	150	01/02/2002	ELECTRIC CHARGE GENERATING SEMICONDUCTOR SUBSTRATE BUMP FORMING DEVICE, METHOD OF REMOVING ELECTRIC CHARGE FROM ELECTRIC CHARGE GENERATING SEMICONDUCTOR SUBSTRATE DEVICE FOR REMOVING ELECTRIC CHARGE FROM ELECTRIC CHARGE GENERATING SEMICONDUCTOR SUBSTRATE, AND ELECT	KANAYAMA, SHINJI
<u>10069401</u>	<u>6830989</u>	150	02/26/2002	METHOD AND APPARATUS FOR HANDLING ARRAYED PART	KANAYAMA, SHINJI
<u>10089184</u>	<u>6692214</u>	150	07/17/2002	PUSHER, PULLER LOADER, UNLOADER, AND WORKING DEVICE	KANAYAMA, SHINJI
<u>10089843</u>	<u>6706130</u>	150	04/04/2002	METHOD AND DEVICE FOR FRICTIONAL CONNECTION AND HOLDING TOOL USED FOR THE FRICTIONAL CONNECTION DEVICE	KANAYAMA, SHINJI
<u>10234118</u>	Not Issued	93	09/05/2002	COMPONENT MOUNTING APPARATUS AND COMPONENT MOUNTING METHOD	KANAYAMA, SHINJI
<u>10239060</u>	Not Issued	94	12/05/2002	APPARATUS AND METHOD FOR MOUNTING COMPONENT	KANAYAMA, SHINJI
<u>10332026</u>	<u>6910613</u>	150	01/02/2003	DEVICE AND METHOD FOR FORMING BUMP	KANAYAMA, SHINJI
<u>10375953</u>	Not Issued	61	02/28/2003	Component mounting tool, and method and apparatus for mounting component using this tool	KANAYAMA, SHINJI
<u>10399915</u>	Not Issued	71	09/30/2003	Electronic component component mounting equipment and component mounting method	KANAYAMA, SHINJI
<u>10419106</u>	Not Issued	161	04/21/2003	Bump joining method	KANAYAMA, SHINJI

<u>10508460</u>	Not Issued	20	10/18/2004	Electronic component mounting method and apparatus and ultrasonic bonding head	KANAYAMA, SHINJI
<u>10651103</u>	Not Issued	94	08/29/2003	BUMP FORMING APPARATUS FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVAL METHOD FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVING UNIT FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, AND CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE	KANAYAMA, SHINJI
<u>10651199</u>	Not Issued	95	08/29/2003	BUMP FORMING APPARATUS FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVAL METHOD FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVING UNIT FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, AND CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE	KANAYAMA, SHINJI
<u>10761412</u>	Not Issued	30	01/22/2004	Method of forming bumps on a wafer utilizing a post-heating operation, and an apparatus therefore	KANAYAMA, SHINJI
<u>10805407</u>	Not Issued	18	03/22/2004	Method and apparatus for handling arrayed components	KANAYAMA, SHINJI
<u>11114084</u>	Not Issued	41	04/26/2005	Apparatus and method for forming bump	KANAYAMA, SHINJI
<u>11216074</u>	Not Issued	20	09/01/2005	Apparatus and method for mounting component	KANAYAMA, SHINJI

Inventor Search Completed: No Records to Display.

Search Another: Inventor	Last Name	First Name	<input type="button" value="Search"/>
	<input type="text" value="KANAYAMA"/>	<input type="text" value="SHINJI"/>	

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | [Home page](#)